

**ARIES ELECTRONICS, INC.
PRODUCTION DEPARTMENT**

PROCEDURE NUMBER: A-548

REV. B

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PROCEDURE NAME: CLEANING PROCEDURE FOR RF MICROSTRIP SOCKETS

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1.0 SCOPE

1.1 THE PURPOSE OF THIS DOCUMENT IS TO DEFINE THE ACCEPTED CLEANING PROCEDURE FOR ARIES' RF MICROSTRIP SOCKETS.

2.0 REFERENCE DOCUMENTS

2.1 ARIES' DATA SHEET 24001

2.2 RDZ-1699 DE-OX II DATA SHEET

2.3 RDZ-1699 DE-OX II MATERIAL SAFETY DATA SHEET

RD CHEMICAL, 1350 PEAR AVENUE, MOUNTAIN VIEW, CA 94043

PH: 650/962-8004, EMAIL: rdchem@rdchem.com, WEB: www.rdchem.com

3.0 MATERIAL REQUIRED

3.1 MICROSTRIP SOCKET

3.2 ISOPROPYL ALCOHOL

3.3 RDZ-1699 DE-OX II

4.0 EQUIPMENT REQUIRED (OR EQUIVALENT)

4.1 B&L STEREOZOOM 4 MICROSCOPE (IF NEEDED)

4.2 TWEEZER

4.3 SMALL STAINLESS STEEL CONTAINER OR GLASS BEAKER

4.4 HOT PLATE

4.5 FIRM-HAIRED SCRATCH BRUSH

4.6 EXACTO KNIFE

5.0 PROCEDURE

5.1 **CAUTION: BE CERTAIN TO HANDLE RDZ-1699 DE-OX II ACCORDING TO MANUFACTURERS MSDS.**

5.2 **NOTE: DO NOT PUSH ON THE MICROSTRIP CONTACTS, OR LATCH THE LID, WHILE THE SOCKET IS REMOVED FROM SHIPPING PLATE OR PCB.**

5.3 WHILE SOCKET IS STILL MOUNTED TO PCB, USE SCRATCH BRUSH AND/OR EXACTO KNIFE TO REMOVE COMPACTED DEBRIS FROM MICROSTRIP CONTACTS. **(ALWAYS SCRUB OR SCRAPE CONTACTS IN PARARELL DIRECTION WITH CONTACTS.)**

5.4 REMOVE SOCKET FROM PCB AND BLOW OFF ANY LOOSE DEBRIS WITH FILTERED AIR.

5.5 POUR RDZ-1699 DE-OX II INTO CONTAINER. MAKE SURE THERE IS ENOUGH TO COVER THE CONTACTS WHEN SOCKET IS IMMERSSED.

5.6 HEAT THE RDZ-1699 DE-OX II ON THE HOT PLATE TO +120°F. **(NOT CELSIUS!)**

5.7 PLACE SOCKET, OR CONTACT BLOCK, INTO CONTAINER AND SOAK FOR 5-6 MINUTES.

(NOTE: DO NOT USE ULTRASONIC CLEANER.)

5.8 REMOVE SOCKET AND RINSE WITH DISTILLED WATER.

5.9 BLOW DRY SOCKET WITH FILTERED AIR AND BAKE SOCKET FOR 10 MINUTES AT 85°C.

5.10 WHILE SOCKET IS DRYING, CLEAN PCB TRACES WITH SCRATCH BRUSH AND ALCOHOL. BLOW DRY WITH FILTERED AIR.

5.11 MOUNT SOCKET BACK ONTO THE PCB AND CONTINUE TESTING.

5.12 REPEAT ABOVE PROCEDURE UNTIL CONTACTS CAN NO LONGER BE USED FOR TEST.